



# Product data sheet

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Semiconductor Compiance

## **FEATURES**

- Low forward voltage
- · High current capability
- High forward surge capability
- Low power losses, High efficiency
- · Guarding for over voltage protection

## **APPLICATIONS**

Low VF Schottky barrier rectifier are designed for high freqency, miniature switched mode power supplies such as adapters, lighting and on-board DC/DC conerters

Primary Characteristic		
lo	2*5A	
V <sub>RRM</sub>	200V	
I <sub>FSM</sub>	130A	
VF	0.72V	
Tյmax	<b>150</b> ℃	
Assembly code	AE	

## **MECHANICAL DATA**

- Case: Molded plastic
- · Polarity: As marked
- Mounting Position: Any
- Molded Plastic: UL Flammability Classification Rating 94V-0
- Lead free in compliance with EU RoHS 2011/65/EU directive
- Solder bath temperature 275 °C maximum, 10s per JESD 22-B106

Characteristics		Symbol	Value	Unit
Maximum Repetitive Peak Reverse Voltage		V <sub>RRM</sub>	200	V
Working Peak Reverse Voltage		V <sub>RWM</sub>	200	V
Maximum DC Blocking Voltage		V <sub>DC</sub>	200	V
	Per Leg		5	
Maximum Average Forward Rectified Current	Total		10	— A
Peak Forward Surge Current,8.3 ms Single Half Sine-wave		I <sub>FSM</sub>	130	A
Operating Temperature Range		TJ	150	°C
Storage Temperature Range		T <sub>STG</sub>	-40 to +150	°C
TypicalThermalResistance(Note1)				
TO-220AB,TO-263,TO-252		R <sub>0 IC</sub>	2	°C/W
TO-220F			4	

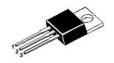
resistance from Junction to case per leg mounte

Characteristics		Symbol	Va	lue	Unit
Forward Voltage Drop(Note2)			Тур.	Max.	
at I⊧=2A	TA=25°C		0.77	-	
	TA=125°C	1 [	0.63	-	
at I⊧=3A	TA=25°C	V <sub>F</sub>	0.80	-	V
	TA=125°C	1 [	0.67	-	
at I⊧=5A	TA=25°C	1 [	0.85	0.92	
	TA=125°C	1 [	0.72	-	
Maximum Reverse Current at $V_R$ =200V	TA=25°C		1	5	μA
	TA=125°C		0.5	-	mA

Note2:Pulse test: 300 µs pulse width, 1 % duty cycle



SCHOTTKY BARRIER RECTIFIER



TO-220AB/CT



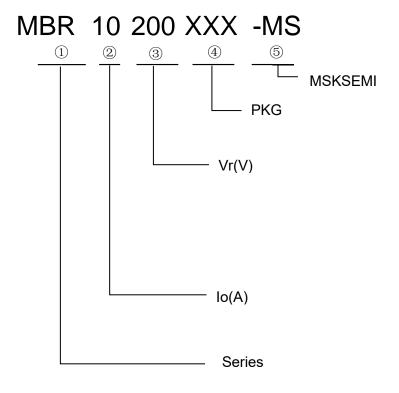
TO-263/DC



3 TO-252/CS

<b>PIN 1</b>	0	1
-		-0
PIN 3	0	PIN 2

#### **P/N Information**

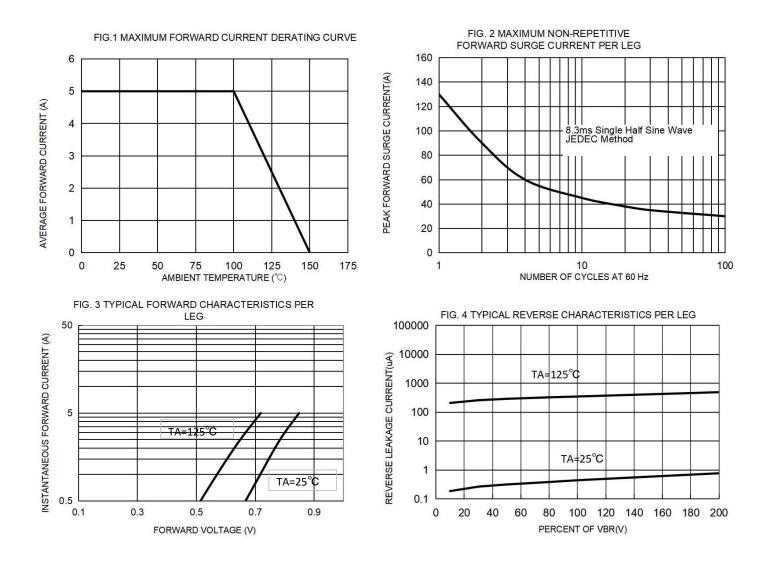


1	2	3	(4)	(5)
系列	平均整流电流	直流反向耐压	封装	MSKSEMI



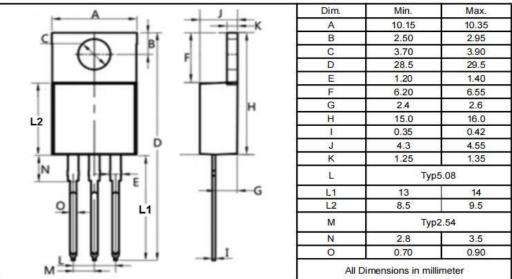
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## RATINGS AND CHARACTERISTIC CURVES





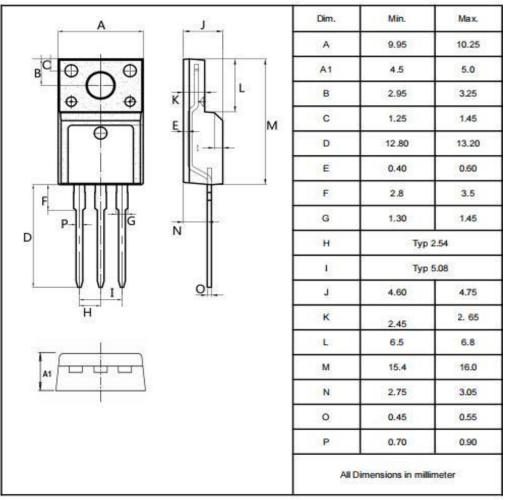
TO-220AB



P/N	PKG	QTY
MBR10200CT-MS	TO-220AB	50pcs/tube 1000pcs/box

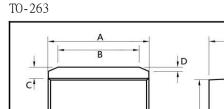


TO-220F



P/N	PKG	QTY
MBR10200FCT-MS	TO-220F	50pcs/tube 1000pcs/box

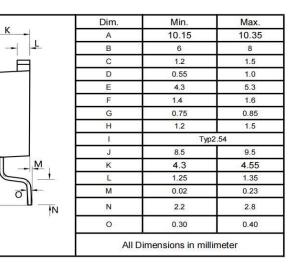




F

4

E



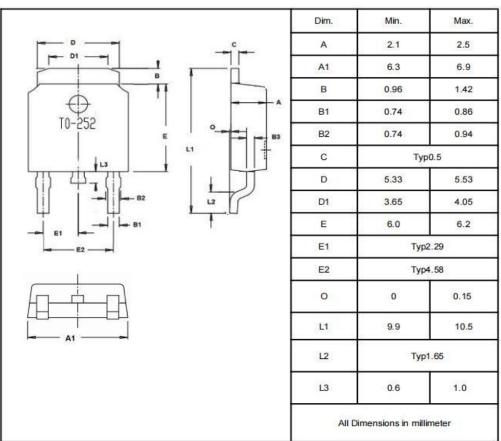
#### **REEL SPECIFICATION**

P/N	PKG	QTY
MBR10200DC-MS	TO-263	50pcs/tube 1000pcs/box

P/N	PKG	QTY
MBR10200DC-R-MS	TO-263	800pcs



TO-252



P/N	PKG	QTY
MBR10200CS-MS	TO-252	2500



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